

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Rajendra D. PENDSE

Application No.: 09/802,664

Filed: March 9, 2001

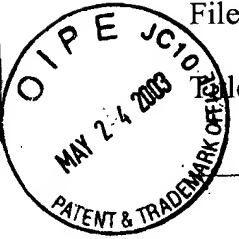
Title: Flip chip interconnection structure

) Examiner: Hsien Ming LEE

) Group Art Unit: 2823

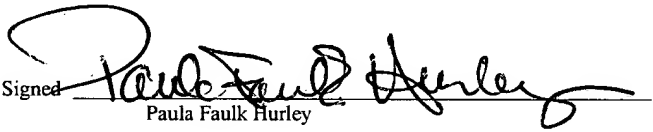
) Date: May 20, 2004

) CERTIFICATE OF MAILING



I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Non Fee Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on May 20, 2004.

Signed


Paula Faulk Hurley

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O. BOX 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

Responsive to the Office action mailed April 28, 2004, kindly amend the application as follows:

Amendments to the Claims are reflected in the **Listing of Claims**, which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.